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ABSTRACT OF THE DISCLOSURE

InsA4)

The layer sequence built on a substrate in thin-layer technology includes an electrically conductive sputtered layer (4) and an electrically conductive reinforcing layer (5) for reinforcing or strengthening the sputtered layer, which is applied by a method other than sputtering. In order to remove conducting material with the aid of a laser for the purposes of adjustment while producing as little contaminating material as possible, the electrically conductive reinforcing layer (5) has a reduced thickness or is completely eliminated in regions (6, 10, 14, 16, 17, 19) of the electrically conductive sputtered layer (4) to be adjusted than in other regions outside of the regions to be adjusted.

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DISCLOSURE - CLAIMS